

Assembly Location Addition for Ceramic Side-Brazed DIP Package

Product Change Notice

PCN1206 (v1.0) November 01, 2012

Overview

The purpose of this notice is to describe an addition to the location of assembly of ceramic packages for the ceramic sidebrazed DIP package for both ARINC 429 and MIL-STD 1553 family of devices.

Description

Holt Integrated Circuits has qualified an alternate source supplier for assembly of devices in the ceramic side-brazed DIP packages. There is no change to the package supplier or to the bill of materials.

Products in ceramic side-brazed DIP packages which have been currently assembled at our primary assembly subcontractor, Golden Altos in Santa Clara, CA can now be assembled at an alternate assembly subcontractor. Millennium Microtech is DSCC qualified with full QML Certification/Qualification in addition to being ISO 9001:2008 registered.

There is no change to Fit, Form, Function, Quality or Reliability of these devices. The products will be fully compliant to all published datasheet specifications. Quality and Reliability will remain at the highest standards already demonstrated with Holt Integrated Circuits' existing products.

Reason

Qualification of an alternate ceramic package assembly site will provide additional capacity and is being added to ensure guaranteed supply of ceramic package products for our customers.

Products Affected

Table 1 summarizes the products affected by this PCN. All parts listed are affected by this change.

Table 1: Products Affected

HI-1565CDI	HI-1567CDI	HI-1570CDI	HI-1574CDI	HI-15530CDI	HI-8282ACDI
HI-1565CDT	HI-1567CDT	HI-1570CDT	HI-1574CDT	HI-15530CDT	HI-8282ACDT
HI-1565CDM	HI-1567CDM	HI-1570CDM	HI-1574CDM	HI-15530CDM	HI-8282ACDM
HI-1566CDI	HI-1568CDI	HI-1573CDI	HI-1579CDI	HI-1581CDI	HI-8282ACDI-10
HI-1566CDT	HI-1568CDT	HI-1573CDT	HI-1579CDT	HI-1581CDT	HI-8282ACDT-10
HI-1566CDM	HI-1568CDM	HI-1573CDM	HI-1579CDM	HI-1581CDM	HI-8282ACDM-10
HI-3182CDI	HI-3282CDI	HI-6010C	HI-8282C	HI-8482C	HI-8596CDI
HI-3182CDT	HI-3282CDT	HI-6010CT	HI-8282CT	HI-8482CM	HI-8596CDT
HI-3182CDM	HI-3282CDM	HI-6010M-01	HI-8282CM	HI-8482CM-01	HI-8596CDM
HI-3183CDI	HI-3282CDI-10	HI-6011CDT	HI-8282CM-01	HI-8482CM-14	
HI-3183CDT	HI-3282CDT-10	HI-8383C	HI-8282CM-03	HI-8482CD	
HI-3183CDM	HI-3282CDM-10	HI-8383CT	HI-8382C	HI-8482CDT	
HI-3189CDI		HI-8383CM	HI-8382CT	HI-8482CDM-01	
HI-3189CDT		HI-8383CM-01	HI-8382CM		
HI-3189CDM		HI-8382CM-21	HI-8382CM-01		
			HI-8382CM-03		

Traceability

A Date Code and Country of Origin will facilitate package traceability. Parts from Table 1 can be shipped from either assembly subcontractor with a Date Code of 1210 or later, beginning November 30, 2012. Product from either assembly subcontractor can be shipped interchangeably.



Qualification Data

l able 2:			
Reliability Test	Results	Results	
	QR-1225 Rev 1.0	QR-1226 Rev 1.0	
	Ceramic SB DIP	Ceramic SB DIP	
	HI-8382CM-03	HI-8282CM-03	
Group-D1	15/0	15/0	
Group-D2	15/0	15/0	
Group-D3	15/0	15/0	
Group-D4	15/0	15/0	
Group-D5	15/0	15/0	
Group-D6	3/0	3/0	
Group-D7	15/0	15/0	

Response

Note: In accordance with JESD46-D, this change is deemed accepted by the customer if no acknowledgement is received within 30 days from this notice.

No response is required. For additional information or questions, please contact:

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Additional Documentation

Below is a list of documents that are associated with this notice:

Revision History

The following table shows the revision history for this document.

Date	Version	Revision Description
11/01/12	1.0	Initial Release